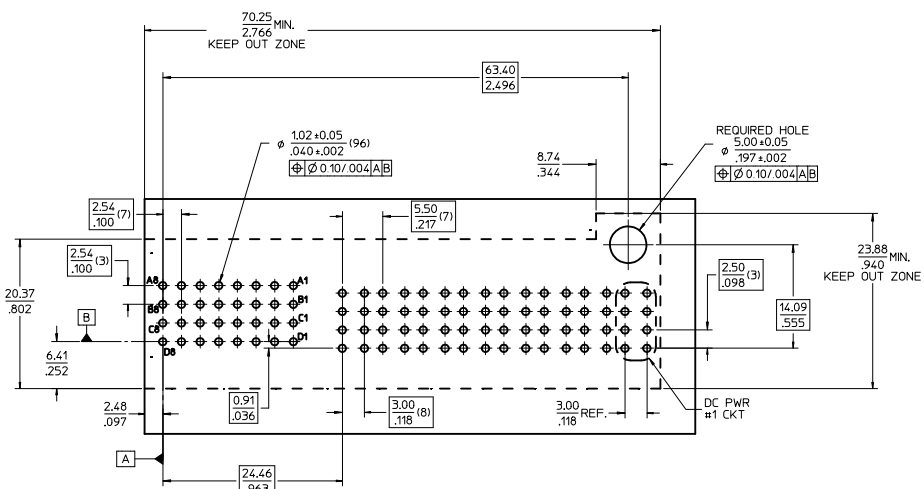


MATING PROFILE (SHOWN MATED TO PLUG ASSY)

VERTICAL ALIGNMENT PARTIAL Z-Z SECTION

SECTION Y-Y

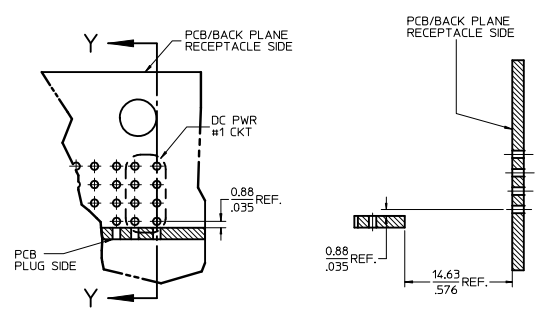
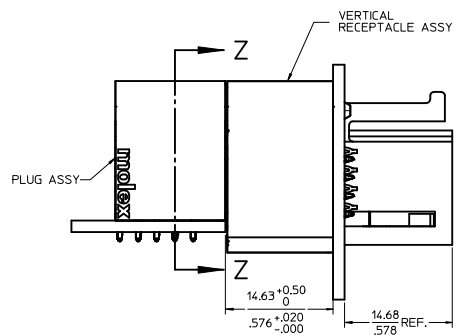
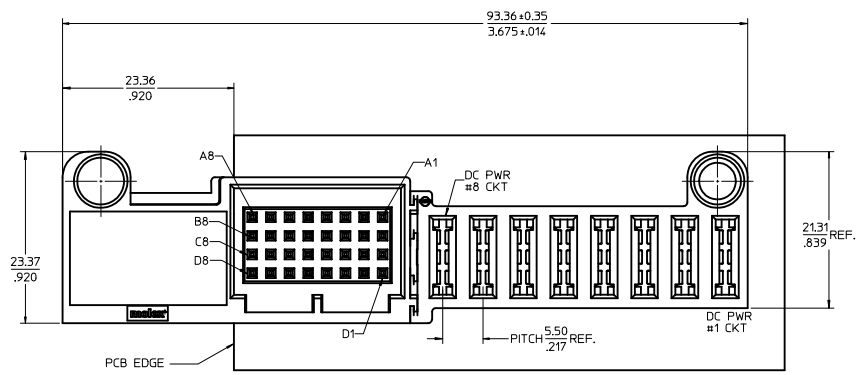
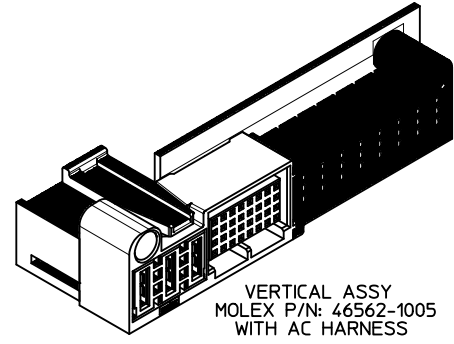
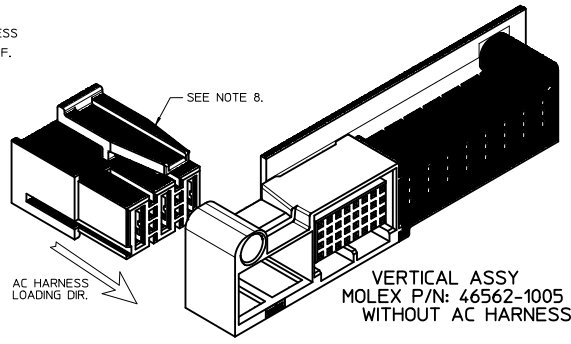
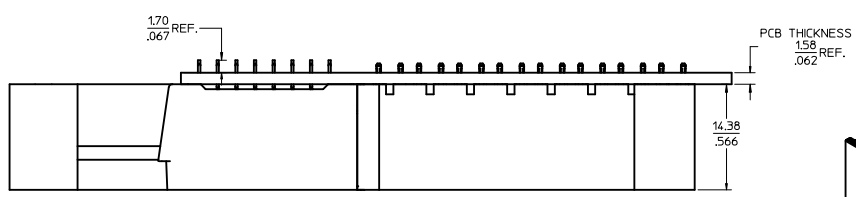


RECOMMENDED PCB LAYOUT AND KEEP OUT ZONE

NOTES:

- MATERIAL:
 - HOUSINGS: HIGH TEMPERATURE PLASTIC BLACK UL-94, V-0 (LCP OR EQUIVALENT).
 - TERMINALS: HIGH CONDUCTIVITY COPPER ALLOY.
 - PLATING: 0.00127/.000050 NICKEL OVERALL WITH 0.00254/.000100 SELECTIVE TIN ON COMPLIANT TAILS AND 0.000762/.000030 SELECTIVE GOLD ON CONTACT AREA.
- PACKAGING: ASSEMBLIES TO BE TRAY PACKED PER PACKAGING SPEC PK-46562-xxx.
- INDIVIDUAL MODULES ARE RATED FOR VARIOUS VOLTAGE AND CURRENT RATINGS PER PS-46436-100.
- PC BOARD REQUIRES SOLDER THRU HOLES. REFER TO PS-46436-100 FOR DETAILS.
- PRODUCT TO MEET ROHS REQUIREMENTS.
- AC HARNESS SOLD SEPARATELY.
- ASSEMBLY MATES TO MOLEX PLUG ASSEMBLY, P/N 46437-1082.
- AC HARNESS MODULE P/N: 46586-1003 SOLD SEPARATELY.

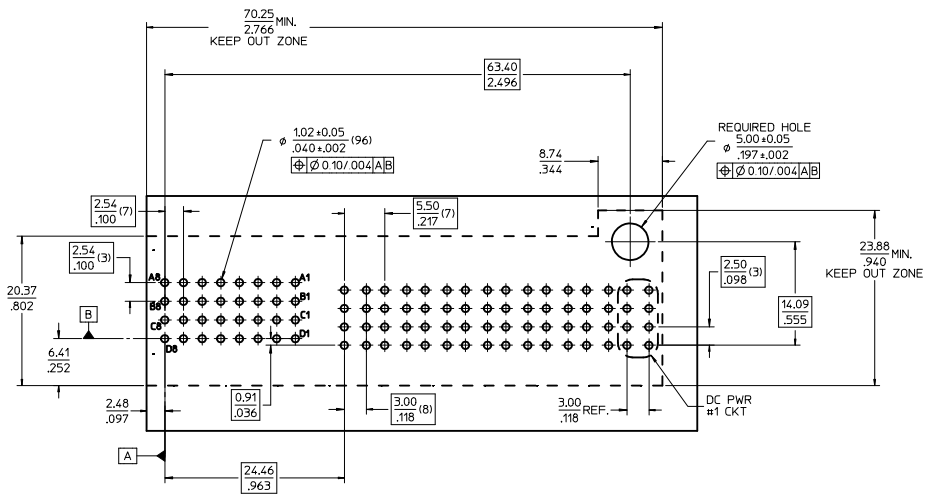
CHNG PLATING SPEC IEC NO: UCP2012-1534 DRAWN BY: SZCZOR CHKD BY: APATEL APPR: APATEL DATE: 2011/11/11 DATE: 2011/11/14	QUALITY SYMBOLS DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ±.--- ±.--- 3 PLACES ±.--- ±.010 2 PLACES ±0.25 ±.010 1 PLACE ±0.25 ±.--- ANGULAR ±1/2°	DRAWN BY DATE BKOSTIC 2007/09/10	TITLE RECEPTACLE ASSY 32S, 8DC PWR AND AC SLOT TEN60 FAMILY, VERTICAL			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY DATE BKOSTIC 2007/10/10	MOLEX INCORPORATED			
		MATERIAL NO. 46562-1005	APPROVED BY DATE APATEL 2011/07/12	DOCUMENT NO. SD-46562-1005	SHEET NO. 1 OF 1		



MATING PROFILE (SHOWN MATED TO PLUG ASSY)

VERTICAL ALIGNMENT PARTIAL Z-Z SECTION

SECTION Y-Y



RECOMMENDED PCB LAYOUT AND KEEP OUT ZONE

NOTES:

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- PACKAGING: ASSEMBLIES TO BE TRAY PACKED PER PACKAGING SPEC PK-46562-xxx.
- INDIVIDUAL MODULES ARE RATED FOR VARIOUS VOLTAGE AND CURRENT RATINGS PER PS-46436-100.
- PC BOARD REQUIRES SOLDER THRU HOLES. REFER TO PS-46436-100 FOR DETAILS.
- PRODUCT TO MEET ROHS REQUIREMENTS.
- AC HARNESS SOLD SEPARATELY.
- ASSEMBLY MATES TO MOLEX PLUG ASSEMBLY, P/N 46437-1082.
- AC HARNESS MODULE P/N: 46586-1003 SOLD SEPARATELY.

CHNG PLATING SPEC IEC NO: UCP2012-1534 DRAWN BY: SZCZOR CHKD BY: APATEL APPR: APATEL DATE: 2011/11/11 DATE: 2011/11/14	QUALITY SYMBOLS DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± .010 3 PLACES ± .010 2 PLACES ± 0.25 1 PLACE ± 0.25	± .010 ± .010 ± .010 ± .010	DRAWN BY BKOSTIC	DATE 2007/09/10	TITLE RECEPTACLE ASSY 32S, 8DC PWR AND AC SLOT TEN60 FAMILY, VERTICAL			
		ANGULAR ± 1/2°		APPROVED BY APATEL	DATE 2011/07/12	MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 46562-1005	DOCUMENT NO. SD-46562-1005	SHEET NO. 1 OF 1			

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